2/9/1

DIALOG(R) File 351: Derwent WPI

(c) 2003 Thomson Derwent. All rts. reserv.

007110283

WPI Acc No: 1987-110280/198716

Related WPI Acc No: 1987-110281; 1987-110282; 1987-110283; 1987-144745;

1987-171610

XRPX Acc No: N87-082981

Movable member mounting for optical beam deflector - has pair of electrically conductive paths formed by doping or metallising portions of assembly

В

Patent Assignee: BRITISH TELECOM PLC (BRTE ); MALLINSON S R (MALL-I)

Inventor: MALLINSON S R; STANLEY I W

Number of Countries: 017 Number of Patents: 034

Patent Family:

Patent No		Kind	Date	Ap	plicat No	Kind	Date	Week
	219356	A	19870422	EP	86308047	A	19861016	198716
WO	8702470	A	19870423	WO	86GB631	A	19861016	198717
WO		Α	19870423	WO	86GB628	A	19861016	198717
WO		Α	19870423	WO	86GB626	A	19861016	198717
WO		A	19870423	WO	86GB630	A	19861016	198717
WO	8702476	Α	19870423	WO	86GB629	A	19861016	198717
WO	8702518	Α	19870423	WO	86GB627	A	19861016	198717
JP	63501382	W	19880526	JP	86505412	A	19861016	198827
JP	63501383	M	19880526	JP	86505474	A	19861016	198827
JP	63501384	W	19880526	JP	86505473	Α .	19861016	198827
JP	63501385	W	19880526	JP	86505411	A	19861016	198827
JP	63501393	W	19880526					198827
JP	63501600	W	19880616					198830
US	4802727	A	19890207	US	8780467	Α	19870611	198908
US	4825262	A	19890425	US	8780468	A	19870611	198919
US	4846930	A	19890711	US	8780564	A	19870611	198935
US	4854658	Α	19890808	US	8780465	A	19870612	198939
US	4867532	A	19890919	US	8780464	A	19870612	198947
ΕP	219356	В	19891206					198949
US	4871244	Α	19891003	US	8780469	A	19870612	198949
DE	3667335	G	19900111		•			199004
DE	3667864	G	19900201					199006
ES	2011773	В	19900216		•			199011
US	4896936	A	19900130	US	89303275	Α	19890130	199012
DE	3669401	G	19900412					199016
ES	2012346	В	19900316					199017
ES	2013599	B	19900516					199025
	1271552		19900710		•			199033
	1276781	С	19901127					199102
	1277525	С	19901211					199104
	1278910	С	19910115					199109
	3677881	G	19910411					199116
	1284372	С	19910521					199125
CA	1333452	С	19941213	CA	520796	Α	19861017	199505

Priority Applications (No Type Date): GB 8525458 A 19851016; GB 8525459 A 19851016; GB 8525460 A 19851016; GB 8525461 A 19851016; GB 8525462 A 19851016; GB 8526189 A 19851023

Cited Patents: 1.Jnl.Ref; EP 40302; US 4115747; US 4450563; GB 2127987; JP 56126818; JP 55096903; US 3040583; US 3387531; DE 3138296; DE 3307669; EP 129048; EP 6042; FR 2549243; JP 59172787; US 4546478; US 4182544; EP 92505; US 4466696

Patent Details:

Patent No Kind Lan Pg Main IPC Filing Notes

```
EP 219356
             A E
   Designated States (National): JP US
WO 8702470
             A E
   Designated States (National): JP US
WO 8702472
             A E
  Designated States (National): JP US
WO 8702474
             A E
  Designated States (National): JP US
WO 8702475
             A E
   Designated States (National): JP US
WO 8702476
             A E
  Designated States (National): JP US
WO 8702518
             A E
  Designated States (Regional): AT BE CH DE ES FR GB GR IT LI LU NL SE
US 4802727
             Α
US 4825262
             Α
                    5
US 4846930
             Α
                    5
US 4854658
             A
                    4
US 4867532
             Α
EP 219356
             B E
  Designated States (Regional): AT BE CH DE ES FR GB GR IT LI LU NL SE
US 4871244
            Α
US 4896936
             Α
                    5
CA 1333452
             С
                      G01J-003/26
```

## Abstract (Basic): EP 219356 A

The assembly has two supports and a movable member mounted by respective connecting members between the supports. The electrical conductivity of the assembly is such that one electrically conductive path extends from a support to the movable member and thereafter to the other support. The resistivity of the path is such that the passage of a working current along the path causes thermal expansion of one or more of the connecting members and the movable member thus causing movement of the movable member relatively to the supports.

The movable member is mounted to each support by a pair of connecting members. All the connecting members are electrically conductive, e.g. for diffraction grating or laser cavity mirror. Abstract (Equivalent): EP 219356 B

An assembly of at least two supports (1, 2) and a movable member (3) mounted by respective connecting members (4, 5, 6, 7) between the supports (1, 2) the electrical conductivity of the assembly being such that at least one electrically conductive path (8 or 9) extends from a support (1 or 2) to the movable member (3) and thereafter to the (1) or another (2) support, the resistivity of the path (8 or 9) being such that the passage of a working curren

## Abstract (Equivalent): US 4896936 A

The component such as a laser chip is secured to the lower side of a bridge-shaped support. At least one of the support and the substrate includes the locator for locating the support in at least one direction relatively to the substrate. The support and component is secured to a substrate with the component located between the support and the substrate.

The locator locates the support in two directions relatively to the substrate. The support and the substrate have complementary locating positions constituting the locator. The locating portions comprise complementary V-shaped ridges and V-shaped recesses.

USE - Accurate mounting of small components to a substrate. US 4871244 A

The movable member mounting uses bridges (4-7) between a pair of supports (1,2). The support (1,2) bridges and mirror (3) are integrally formed from a silicon substrate. A pair of electrically conductive

paths (8,9) are formed by doping or metallising portions of the assembly so that by passing controlled currents through the paths, thermal expansion of parts of the paths will cause deflection of the mirror (3).

The assembly is particularly useful for deflecting optical beams. USE - Optical mirror.

US 4867532 A

The device comprises a single crystal silicon substrate (1) having a square recess (2) in which a central upstanding ridge (3) integrally formed with the base is provided. On either side of the ridge are mounted respective electrode plates (4,5). A torsion plate. (6) is integrally formed with the support ridge and has a pair of torsion bars (7,8) and a central square portion (9) carrying a diffraction grating. A deflectable wavelength selection member is constituted by the diffraction grating. The electrode are responsive to a control current to cause the torsion member to deflect whereby radiation centred on a predetermined wavelength is selected from radiation having a number of wavelengths impinging on the selection member by setting the selection member at a predetermined angle to the incoming radiation.

USE - Laser chip external cavity, optical communications source for direct detection or coherent systems.

US 4854658 A

The radiation deflector assembly, primarily for deflecting optical radiation, includes there waveguides mounted in V-shaped grooves (2, 3, 4) of a substrate (1) which are coplanar. A cantilevered beam integral with the substrate (1) is positioned in a cavity (5) of the substrate such that when the beam (6) is in a first position radiation passes between optical waveguides in two of the grooves (2, 3) and when the beam is in a second position optical radiation passes between optical waveguides in another two of the grooves (2, 4).

Control electrodes (8, 9) are responsive to control signals to generate a suitable electrostatic field for moving the beam (6) between the two positions.

USE - For optical switch array.

US 4846930 A

The method of mounting a component e.g. a laser chip, on a substrate, comprises a step of mounting the component on an undersurface of a bridge-shaped support. The support is positioned on substrate with the component located between the support and the substrate. At least one of the support and support is located in at least one direction relatively to the substrate. The support is secured substrate.

Prior to the positioning step, the locator is provided by forming locating portions in the support and the substrate.

US 4825262 A

The Fabry-Perot interferometer comprises a single crystal silicon substrate (1) with an integrally formed diaphragm (6) supported between walls (2-5). A glass superstrata (14) is mounted adjacent the substrate (1) with a spacer (13) sandwiched therebetween.

Facing surfaces (12,16) of the diaphragm (6) and superstrata (14) are polished and suitably coated to define reflective surfaces and the position of the diaphragms may be altered to vary the response of the interferometer.

ADVANTAGE - Enhanced accuracy.

US 4802727 A

A method of positioning an optical component such as a laser diode (36) in alignment with an optical waveguide (30) comprises forming an elongate V-shaped groove (29) and a depression (31) in a substrate (28). A laser diode is then mounted in the depression (31) and is accurately located there.

An optical fibre (30) is mounted in the groove (29). The relative

positions of the depression and the waveguide are such that in use an optical beam may be coupled between the optical component and the waveguide.

ADVANTAGE - Enables optical component to be mounted in same substrate as other optical devices.

Title Terms: MOVE; MEMBER; MOUNT; OPTICAL; BEAM; DEFLECT; PAIR; ELECTRIC; CONDUCTING; PATH; FORMING; DOPE; METALLISE; PORTION; ASSEMBLE

Derwent Class: P78; P81; V07; V08

International Patent Class (Main): G01J-003/26

International Patent Class (Additional): B44C-001/22; G01B-009/02; G02B-002/08; G02B-006/38; G02B-026/02; G02B-026/04; G02B-027/44;

G02F-001/21; H01L-021/30; H01L-023/02; H01S-003/10

File Segment: EPI; EngPI

Manual Codes (EPI/S-X): V07-K04; V07-K05; V08-A01A; V08-A03